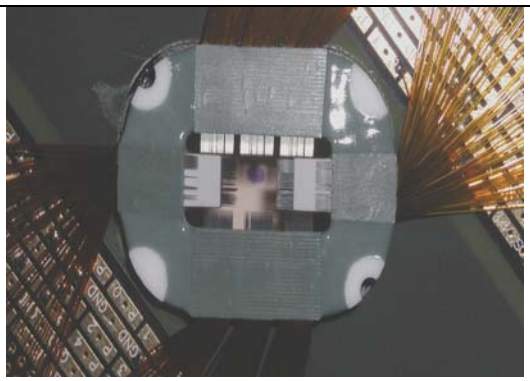
Cantilever 'Shelf' Probe Card Product Specification

ProbeLogic utilizes the latest State-of-the-Art Technology and Equipment to engineer, design, and manufacture high quality and "100% Tested" probe cards. ProbeLogic has the shortest turn-times and the most cost effective test solutions in the industry.



Components/Rings

Rings / Spiders	Ceramic, Aluminum, or Composite Material. (Design Per Customer Spec.)
Shelf Configurations	1x2 to 1x8 in-line; 2x2 Quad
Probe Material	Tungsten, Rhenium Tungsten, Beryllium Copper, and Palladium
Testing Temperature	25°C to 120°C
Probe Diameter	3 mils to 15 mils
Tip Diameter	0.5 mils to 10 mils
Tip Shape	Flat, Etching, or Radius
Tip Length	7 mils (or Build to Customer Spec.)
Contact Resistance	2.0 ohms
Edge Sensors	2 Wire (Left or Right Hand), 2 or 3 Wire Isolated

Devices

Device Types	Logic, Mix-Signal, Memory, LCD
Pad Configuration	Single or Staggered Row
Pad Pitch/Size	Pitch: ≥ 40 microns Width: ≥ 50 microns Length: ≥ 50 microns
Pad Material	Gold Pads, Gold Bumps, Aluminum, Copper (or Industry Standard)

Assembly

Alignment	+/- 0.2 mils
Planarity	+/- 0.2 mils
Probe Depth	80 mils to 150 mils (or Build to Customer Spec.) (Measured from tip to bottom of PCB)
Contact Force	0.8 – 3.0 G/mils O.D.
Epoxy Clearance	11 mils (Measured from tip to closest epoxy surface)
Edge Sensor Setting	*On with First Probe +/- 0.2 mils *Off with Last Probe +/- 0.2 mils
Theta Orientation	0° (+/- 0.5°)

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